



U.S. UTILITY Patent Application

O.I.P.E

PATENT DATE

SCANNED BY

Q.A. Smith

APPLICATION NO. 09/609347	CONT/PRIOR D	CLASS 204	SUBCLASS <u>212</u>	ART UNIT <u>124</u> <u>153</u>	EXAMINER <u>Smith Hicks</u> <u>Mutschler</u>
APPLICANTS		Robin Cheung, Ashok Sinha Avi Tepman Dan Carl			
TITLE		Apparatus for electro chemical deposition of copper metallization with the capability of in-situ thermal annealing			

PTO-2040
12/99

ISSUING CLASSIFICATION

Continued on Issue Slip Inside File Jacket

<input checked="" type="checkbox"/> TERMINAL DISCLAIMER		DRAWINGS			CLAIMS ALLOWED	
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.		Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
					NOTICE OF ALLOWANCE MAILED	
<input checked="" type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. 6,136,163		(Assistant Examiner)	(Date)			
					ISSUE FEE	
					Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.		(Primary Examiner)	(Date)		ISSUE BATCH NUMBER	
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